The Technology Development group's Thin Films division of Intel Corporation currently has openings for physical science Ph.D.s to support/direct R&D of advanced processing methods. Candidates hired for these positions will be responsible for developing the next generation of Intel's microprocessors.

Ph.D. candidates in Physics, Chemistry, Materials Science, Chemical Engineering, Electrical Engineering, Mechanical Engineering, or related fields are encouraged to apply. Criteria for selection include: a strong academic record, demonstrated experimental and data analysis expertise, superior critical thinking skills, an ability to drive and take responsibility for projects and a solid peer-reviewed publication record. Experience using and maintaining scientific equipment is preferred. Semiconductor processing experience is not mandatory.

Openings are immediately available at Intel’s primary development facility (Ronler Acres) located ~10 miles west of Portland, OR. Please see a more detailed job description included below.

Interested candidates should email resumes to CMPHiring@intel.com.

Nikhil Bhole, Ph.D.
TD Senior Module Engineer
Intel Corporation

PTD Module & Integration Device Yield Engineer - JR0001698

Description

PTD Module Engineers are responsible for leading scientific research and enabling manufacture of innovative device architectures coupled with the realization of these architectures. Responsibilities include designing, executing and analyzing experiments necessary to meet engineering specifications for their process. A Module Engineer participates in the development of intellectual property and the development of the equipment necessary to exploit understanding gained in research (in collaboration with equipment suppliers.) The Engineer must work effectively with the equipment supplier to identify shortcomings, propose and evaluate hardware modification to mitigate issues and operate the manufacturing line in order to integrate the many individual steps necessary for the manufacture of complex microprocessors. Module Engineers are also responsible for overseeing in-situ ramp to manufacturing volumes to demonstrate that the technology meets requirements while simultaneously transferring the technology to counterparts in manufacturing via 'Copy Exactly!' methodology. Module ownership includes the install and qualification of manufacturing capacity at the development site and audit installation/qualification and supervision of first full loop at the production site. Must hold a PhD.
Qualifications

You must possess a minimum of a Ph.D. degree majoring in Physics, Material Science, Chemical Engineering, Electrical Engineering, Mechanical Engineering, Chemistry, or a related field.

Criteria for selection include: a strong academic record, demonstrated experimental and data analysis expertise, superior critical thinking skills, excellent written and verbal communication skills, creativity and flexibility to thrive under changing priorities, strong teamwork skills, an ability to drive and take responsibility for projects and a solid peer-reviewed publication record. Experience using and maintaining scientific equipment is preferred. Semiconductor processing experience is not mandatory.

Job Category

Engineering

Primary Location

USA-Oregon, Hillsboro

Full/Part Time

Full Time

Posting Date

August 2016

Apply Before

July 2017

Business Group

As the world's largest chip manufacturer, Intel strives to make every facet of semiconductor manufacturing state-of-the-art -- from semiconductor process development and manufacturing, through yield improvement to final test and optimization, and lastly packaging. Employees in the Technology and Manufacturing group are part of a worldwide network of manufacturing and assembly/test facilities.

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